



GP
ELECTRONICS

GPM090N04LQA
40V N-Channel MOSFET

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
40V	7.0mΩ@10V	25A
	9.0mΩ@4.5V	

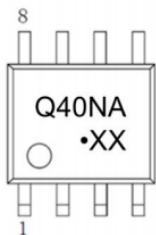
Feature

- High density cell design for ultra low $R_{DS(ON)}$
- Excellent package for good heat dissipation

Application

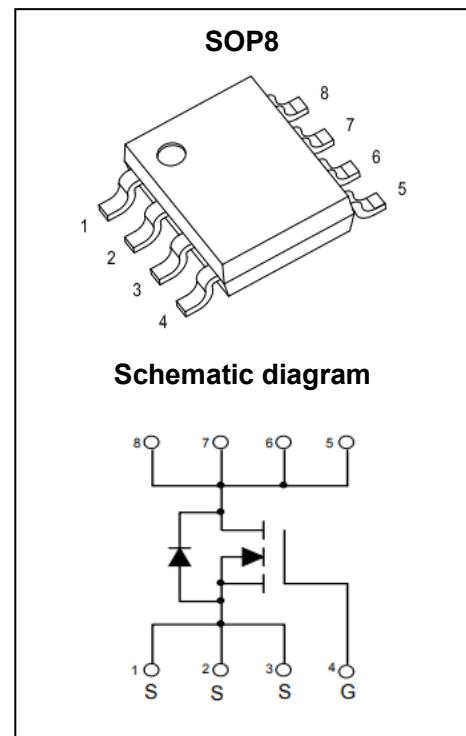
- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

MARKING:



Q40NA = Device Code

XX = Date Code



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	Value	Unit
Drain-Source Voltage		V_{DS}	40	V
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current	$T_c = 25^\circ\text{C}$	I_D	25	A
	$T_c = 100^\circ\text{C}$		17.5	A
Pulsed Drain Current		I_{DM}	110	A
Single Pulsed Avalanche Energy		E_{AS}^*	100	mJ
Power Dissipation	$T_c = 25^\circ\text{C}$	P_D	3.1	W
Thermal Resistance from Junction to Ambient ¹		R_{eJA}	41	°C/W
Junction Temperature		T_J	150	°C
Storage Temperature		T_{STG}	-55~+150	°C

* E_{AS} Test Condition $V_{DD} = 25\text{V}$, $V_{GS} = 10\text{V}$, $L = 0.5\text{mH}$, $I_{AS} = 20\text{A}$ Starting $T_J = 25^\circ\text{C}$.

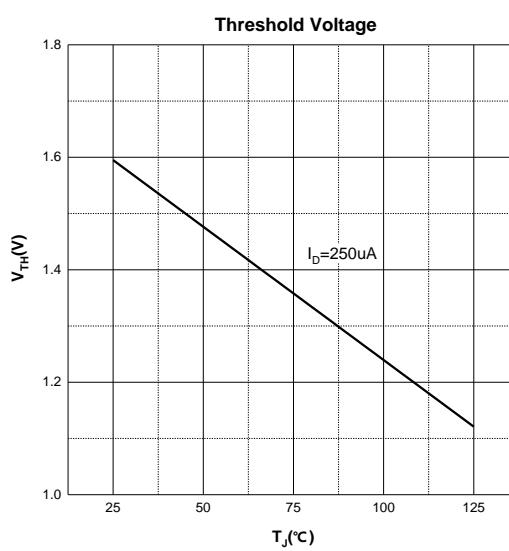
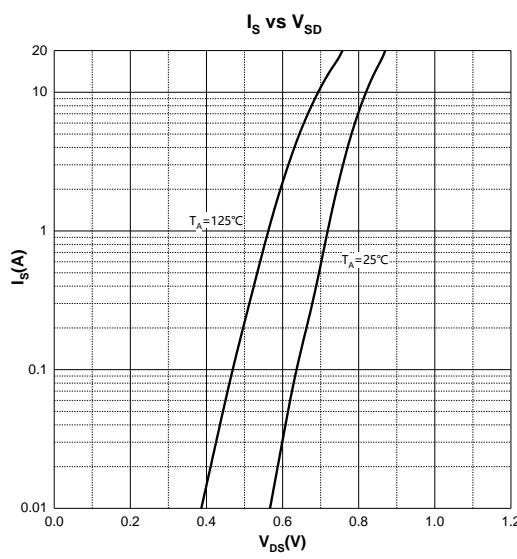
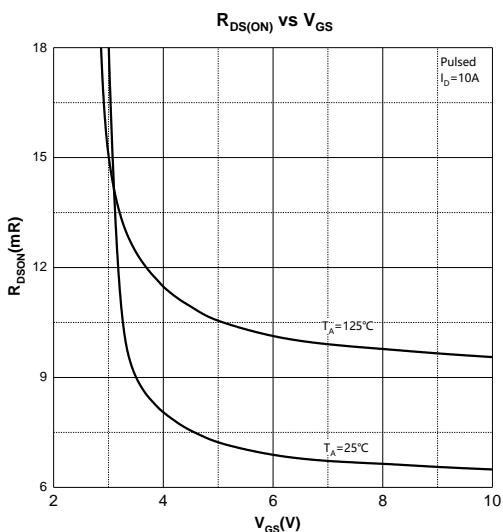
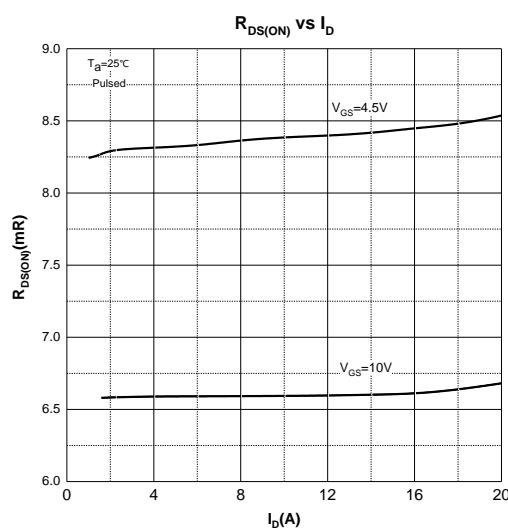
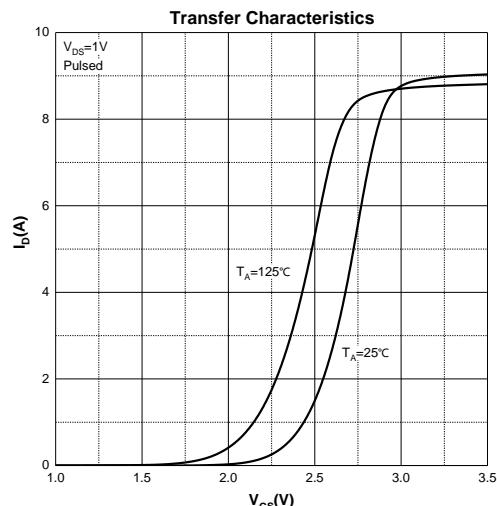
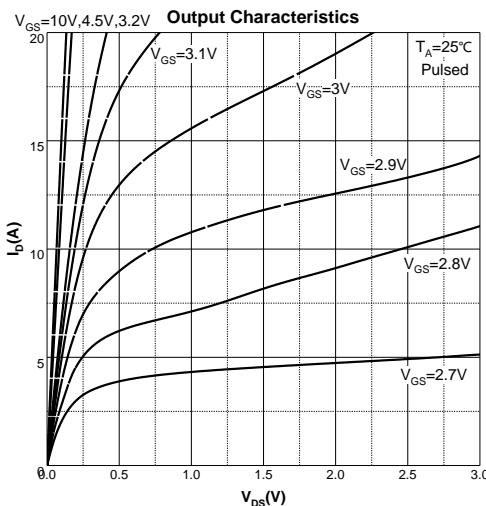
MOSFET ELECTRICAL CHARACTERISTICS($T_A = 25^\circ\text{C}$ unless otherwise noted)

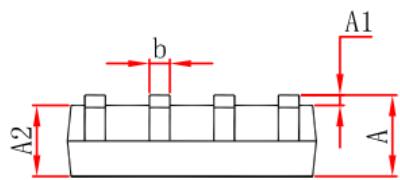
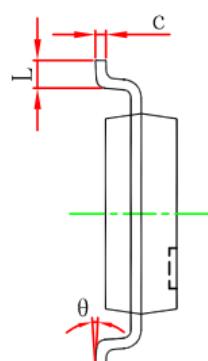
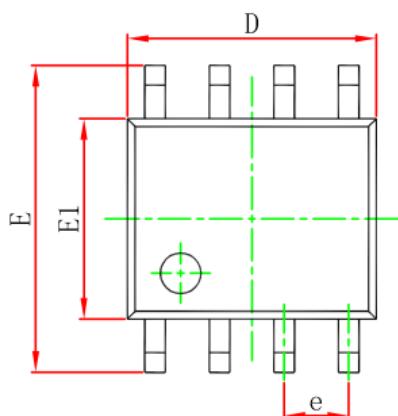
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Off Characteristics						
Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	40			V
Zero gate voltage drain current	I_{DSS}	$V_{\text{DS}} = 40\text{V}, V_{\text{GS}} = 0\text{V}$			1	μA
Gate-body leakage current	I_{GSS}	$V_{\text{GS}} = \pm 20\text{V}, V_{\text{DS}} = 0\text{V}$			± 100	nA
On Characteristics						
Gate threshold voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1	1.5	2.5	V
Drainsource onresistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 10\text{A}$		7	9	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_D = 10\text{A}$		9	13.5	
Forward transconductance	g_{FS}	$V_{\text{DS}} = 10\text{V}, I_D = 10\text{A}$		13		S
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{\text{DS}} = 20\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$		2775		pF
Output Capacitance	C_{oss}			195		
Reverse Transfer Capacitance	C_{rss}			165		
Gate resistance	R_g	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$		1.72		Ω
Switching Characteristics						
Total Gate Charge	Q_g	$V_{\text{DS}} = 20\text{V}, V_{\text{GS}} = 10\text{V}, I_D = 10\text{A}$		20		nC
GateSource Charge	Q_{gs}			3.5		
GateDrain Charge	Q_{gd}			5		
Turnon delay time	$t_{d(\text{on})}$	$V_{\text{DD}} = 15\text{V}, R_G = 3\Omega, V_{\text{GS}} = 10\text{V}, R_L = 3\Omega$		12		ns
Turnon rise time	t_r			3		
Turnoff delay time	$t_{d(\text{off})}$			50		
Turnoff fall time	t_f			5		
Diode Characteristics						
Diode Forward Voltage	V_{SD}	$V_{\text{GS}} = 0\text{V}, I_S = 10\text{A}$			1.2	V

Notes :

1. $R_{\theta\text{JA}}$ is measured with the device mounted on 1 in² FR4 board with 1oz. single side copper, in a still air environment with $T_A = 25^\circ\text{C}$.

Typical Characteristics



SOP8 Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D	4.800	5.000	0.189	0.197
e	1.270 (BSC)		0.050 (BSC)	
E	5.800	6.200	0.228	0.244
E1	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°